

1. Features:

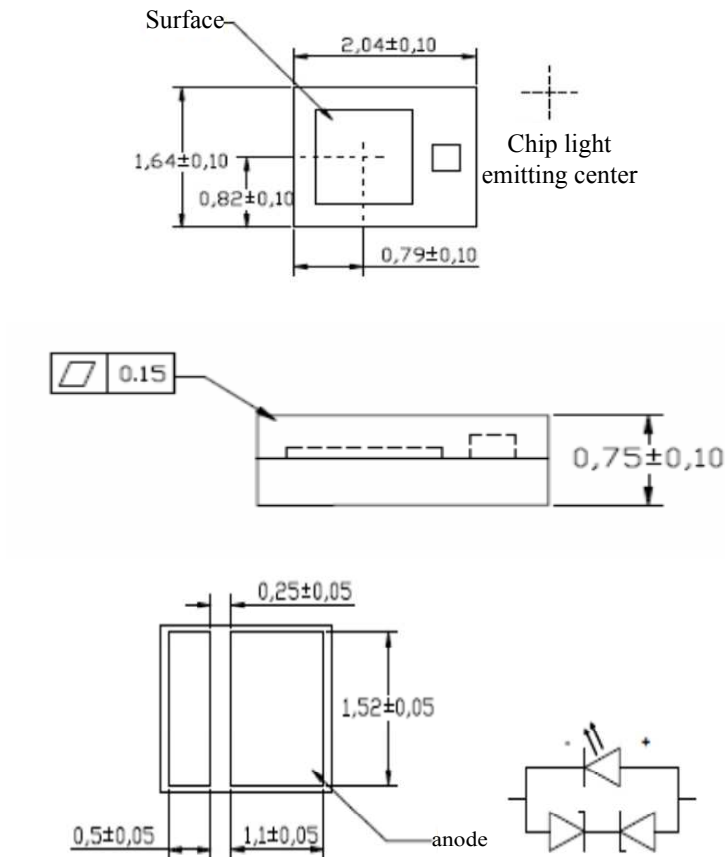
- Small footprint package, High brightness, High efficiency
- Very small emitter size: 2.04 mm × 1.64 mm
- ESD protection up to 8 KV
- Typical color temperature: 5700 k
- Soldering method: SMT
- Typical luminous flux: 220 lm@1000mA



2. Application:

- Mobile phone flash
- Automotive
- General lighting

3. Dimensions:



Notes:

1. Dimensions are in millimeters.
2. Tolerances unless dimensions ± 0.1 mm

4. Electro-Optical Characteristics (T_{solder pad} =25 °C)

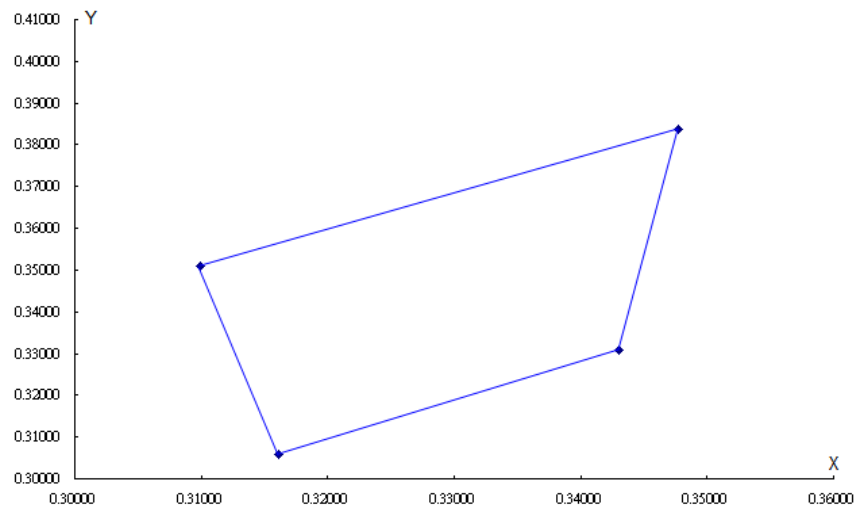
Parameter	Min.	Typ.	Max.	Unit	Condition
Luminous Flux	180	220	----	lm	I _F =1000mA
Forward Voltage	3.0	3.3	3.6	V	
Color Temperature	5000	5700	6500	K	
Viewing Angle	----	120	----	°	
Junction Temperature	----	125	----	°C	
Pulsed Forward Current (400ms : ON 30% duty)	----	1000	----	mA	
Thermal Resistance	----	10	----	°C/W	
Reverse Voltage	----	5	----	V	
Operating Temperature Range	- 40	----	85	°C	
Storage Temperature	- 40	----	110	°C	

Parameter	Min.	Typ.	Max.	Unit	Condition
Luminous Flux	122	150	----	lm	I _F =500mA
Forward Voltage	2.9	3.1	3.3	V	
Correlated Color Temperatere	4900	5600	6400	K	

Note :

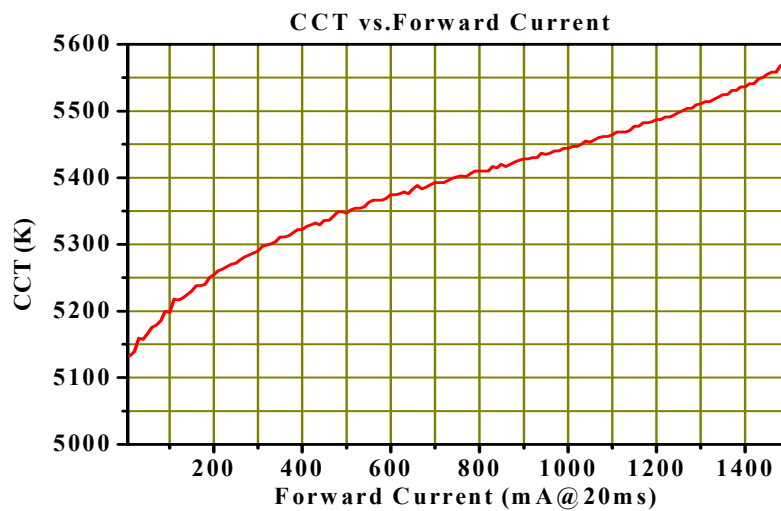
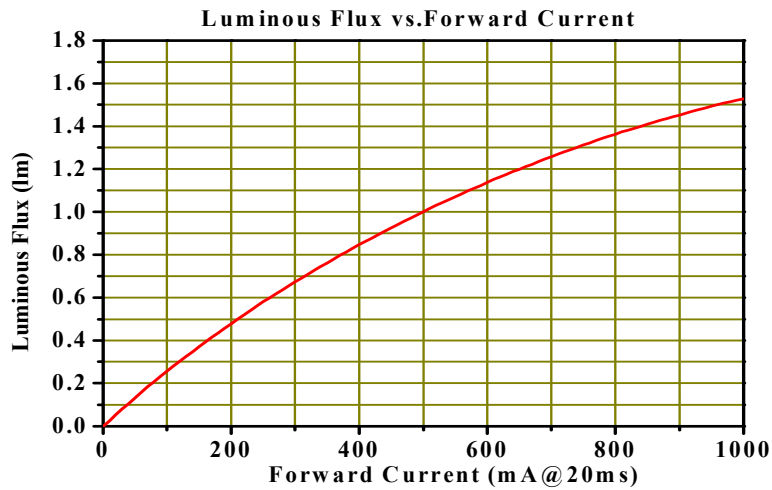
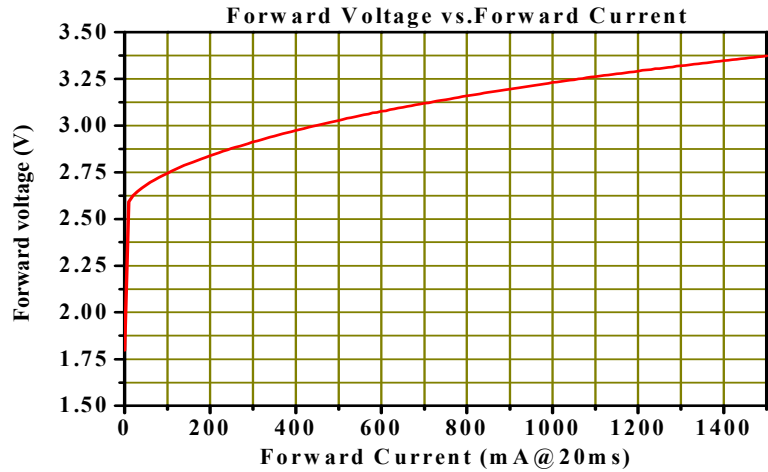
- 1.Luminous flux measurement tolerance: ±10%
2. Forward voltage measurement tolerance: ± 0.1V
3. Electric and optical data is tested at 20 ms pulse condition

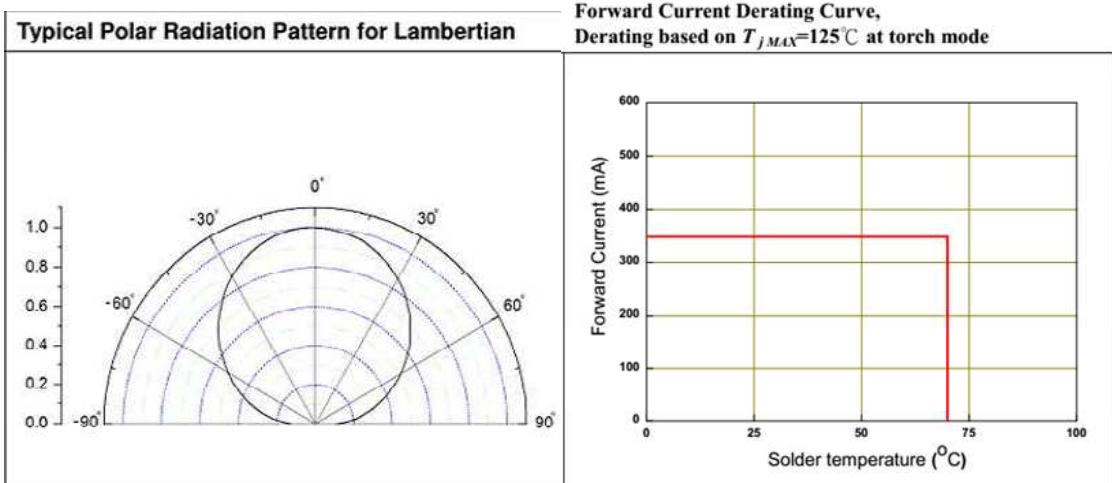
5. Color Binning



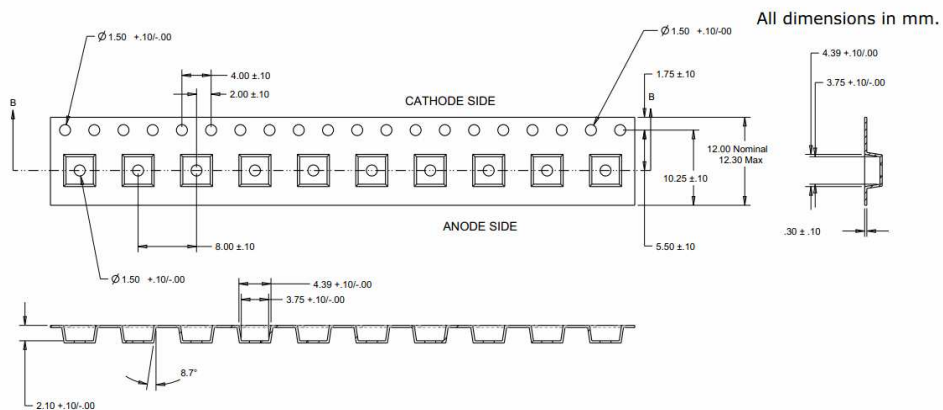
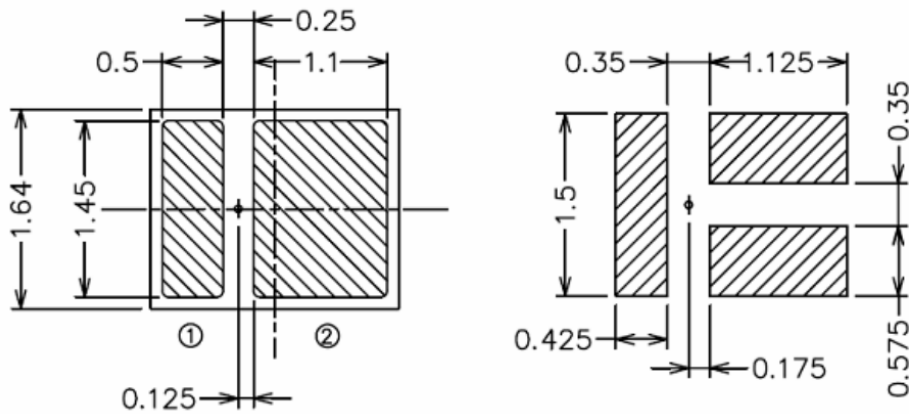
6. Typical Electro-Optical Characteristics Curves

($I_F=1000\text{mA}@20\text{ms}$, $T_{\text{solder pad}}=25\text{ }^\circ\text{C}$)





7. Pad Dimensions



8. Reel Dimensions

